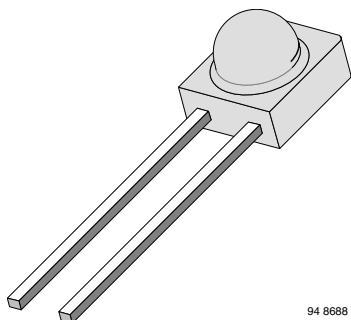


High Speed Infrared Emitting Diode, RoHS Compliant, 890 nm, GaAIAs Double Hetero



DESCRIPTION

TSSF4500 is an infrared, 890 nm emitting diode in GaAIAs double hetero (DH) technology with high radiant power and high speed, molded in a clear, untinted plastic package.

FEATURES

- Package type: leaded
- Package form: side view
- Dimensions (L x W x H in mm): 4.5 x 4 x 4.8
- Peak wavelength: $\lambda_p = 890$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\varphi = \pm 22^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- High modulation bandwidth: $f_c = 12$ MHz
- Good spectral matching with Si photodetectors
- Lead (Pb)-free component in accordance with RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS
COMPLIANT

APPLICATIONS

- Infrared high speed remote control and free air data transmission systems with high modulation frequencies or high data transmission rate requirements
- TSSF4500 is ideal for the design of transmission systems according to IrDA requirements and for carrier frequency based systems (e.g. ASK/FSK - coded, 450 kHz or 1.3 MHz)

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	φ (deg)	λ_p (nm)	t_r (ns)
TSSF4500	20	± 22	890	30

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TSSF4500	Bulk	MOQ: 4000 pcs, 4000 pcs/bulk	Side view

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I_{FM}	200	mA
Surge forward current	$t_p = 100 \mu s$	I_{FSM}	1.5	A
Power dissipation		P_V	160	mW



ABSOLUTE MAXIMUM RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	- 40 to + 100	°C
Storage temperature range		T_{stg}	- 40 to + 100	°C
Soldering temperature	$t \leq 5$ s, 2 mm from case	T_{sd}	260	°C
Thermal resistance junction/ambient	Leads not soldered	R_{thJA}	450	K/W

Note

$T_{amb} = 25$ °C, unless otherwise specified

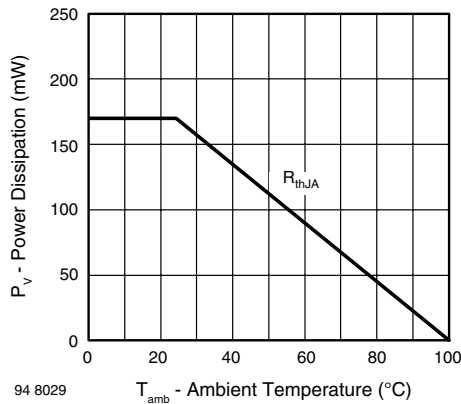


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

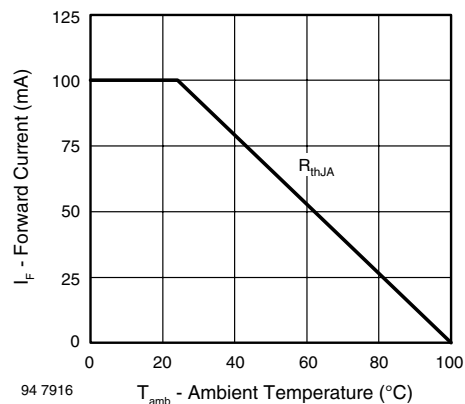


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100$ mA, $t_p = 20$ ms	V_F		1.35	1.6	V
	$I_F = 1.5$ A, $t_p = 100$ μ s	V_F		2.4		V
Temperature coefficient of V_F	$I_F = 1$ mA	TK_{V_F}		- 1.8		mV/K
Reverse current	$V_R = 5$ V	I_R			10	μ A
Junction capacitance	$V_R = 0$ V, $f = 1$ MHz, $E = 0$	C_j		160		pF
Radiant intensity	$I_F = 100$ mA, $t_p = 20$ ms	I_e	10	20	50	mW/sr
	$I_F = 1$ A, $t_p = 100$ μ s	I_e		200		mW/sr
Radiant power	$I_F = 100$ mA, $t_p = 20$ ms	ϕ_e		35		mW
Temperature coefficient of ϕ_e	$I_F = 100$ mA	TK_{ϕ_e}		- 0.7		%/K
Angle of half intensity		ϕ		± 22		deg
Peak wavelength	$I_F = 100$ mA	λ_p		890		nm
Spectral bandwidth	$I_F = 100$ mA	$\Delta\lambda$		40		nm
Temperature coefficient of λ_p	$I_F = 100$ mA	TK_{λ_p}		0.2		nm/K
Rise time	$I_F = 100$ mA	t_r		30		ns
Fall time	$I_F = 100$ mA	t_f		30		ns
Cut-off frequency	$I_{DC} = 70$ mA, $I_{AC} = 30$ mA pp	f_c		12		MHz
Virtual source diameter		d		2.1		mm

Note

$T_{amb} = 25$ °C, unless otherwise specified

BASIC CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

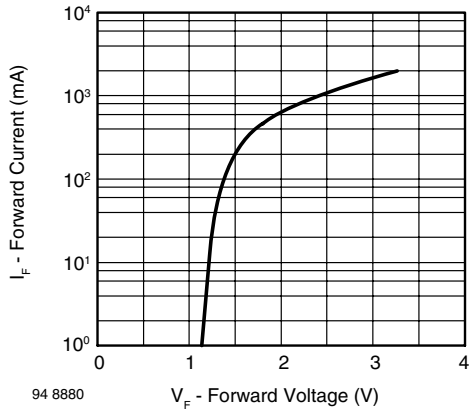


Fig. 3 - Forward Current vs. Forward Voltage

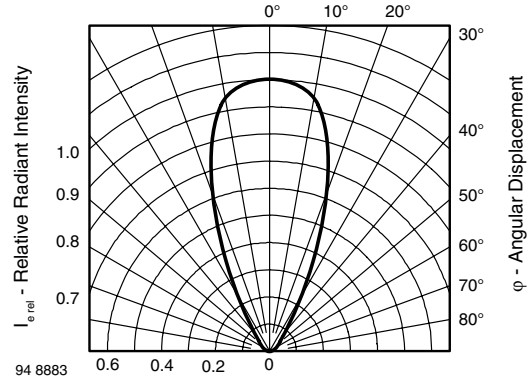


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

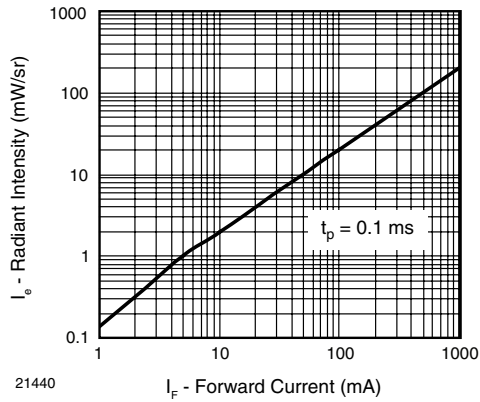


Fig. 4 - Radiant Intensity vs. Forward Current

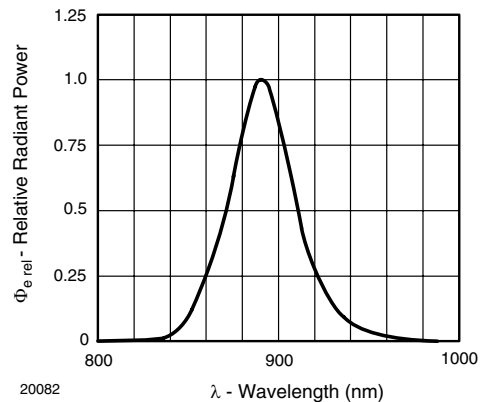
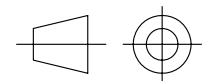
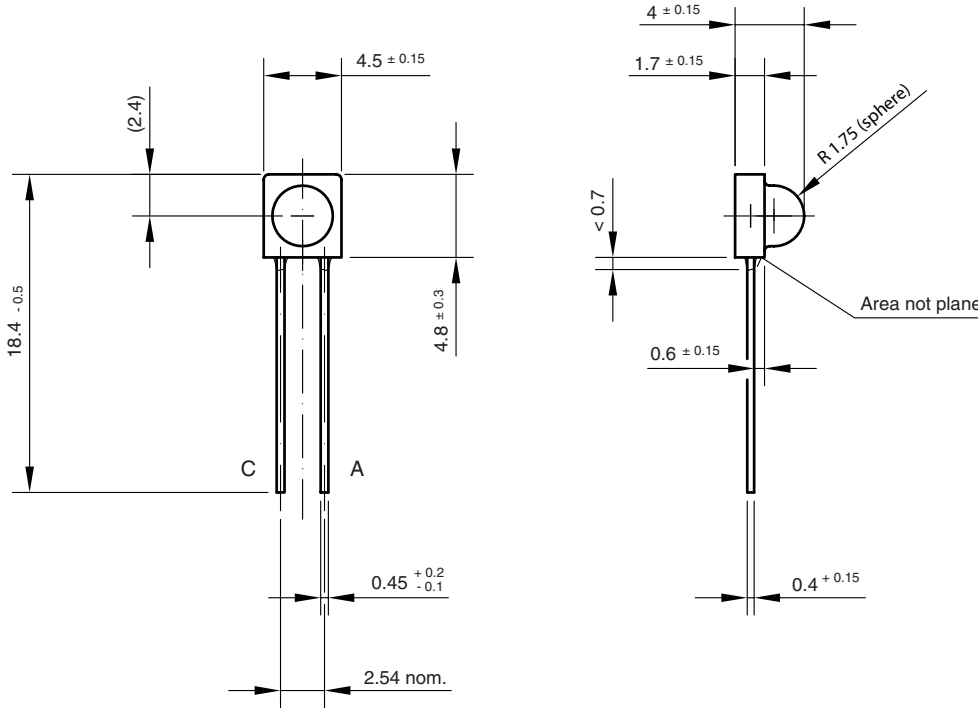


Fig. 5 - Relative Radiant Power vs. Wavelength



PACKAGE DIMENSIONS in millimeters



technical drawings
according to DIN
specifications

Drawing-No.: 6.544-5253.01-4
Issue:1; 01.07.96
96 12206



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